



PRESS RELEASE

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TechSearch International, Inc. Examines Advanced Packaging's Growth in AI

TechSearch International's latest analysis examines demand for packages used in AI. As the industry enters the AI era, successful hardware deployment requires a supply of silicon interposers, or alternatives such as redistribution layer (RDL) structures and advanced laminates, to support high density. With the desire to add more and more high bandwidth memory (HBM) stacks, the size of the interposers is growing, driving demand for larger build-up package substrates. TechSearch International analyzes industry readiness with silicon interposers (and alternatives), large body-size packages, and HBM. Reliability issues for large body size packages are highlighted. Demand projections are provided for interposers and HBM. Supply and demand for build-up substrates is examined, given the need for large substrates. The report also examines the status of glass for substrates and provides an update on the technology. The report points out challenges to be addressed.

While wafer-to-wafer (W2W) hybrid bonding has been in production for image sensors for many years, and is seeing growing use in the production of NAND Flash, die-to-wafer (D2W) adoption is in the early stages. The report analyzes the adoption for memory on logic, logic on logic, and the future for HBM. Research activities and challenges are discussed.

RF package trends are highlighted with an in-depth examination in the mobile space. Alternatives to laminate substrates are discussed. The report examines OSAT financials, discussing prospects for the year.

The latest Advanced Packaging Update is a 110-page report with full references and an accompanying set of ~100 PowerPoint slides.

TechSearch International, Inc., founded in 1987, is a market research leader specializing in technology trends in microelectronics packaging and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International professionals have an extensive network of more than 22,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch at tel: 512-372-8887 or see www.techsearchinc.com. Follow us on LinkedIn.